

L Number	Hits	Search Text	DB	Time stamp
1	2	("5319759").PN.	USPAT; EPO; JPO; DERWENT; USOCR	2003/10/13 17:14
2	2	("5319159").PN.	USPAT; EPO; JPO; DERWENT; USOCR	2003/10/13 17:21
3	20	5319159.URPN.	USPAT	2003/10/13 17:17
4	12449	substrate and anisotropical\$3	USPAT; EPO; JPO; DERWENT; USOCR	2003/10/13 17:21
5	9535	substrate and (anisotropical\$3 adj etch\$3)	USPAT; EPO; JPO; DERWENT; USOCR	2003/10/13 17:59
6	1714	(substrate and (anisotropical\$3 adj etch\$3)) and pad	USPAT; EPO; JPO; DERWENT; USOCR	2003/10/13 17:22
7	1319	((substrate and (anisotropical\$3 adj etch\$3)) and pad) and insulat\$4	USPAT; EPO; JPO; DERWENT; USOCR	2003/10/13 17:23
8	3	174/\$.ccls. and (((substrate and (anisotropical\$3 adj etch\$3)) and pad) and insulat\$4)	USPAT; EPO; JPO; DERWENT; USOCR	2003/10/13 17:23
9	16	("3365620" "3698082" "3757175" "3777221" "3936866" "3947957" "4017886" "4189825" "4221047" "4256532" "4259684" "4264917" "4285002" "4294009" "4361720" "4396936").PN.	USPAT	2003/10/13 17:25
10	34	4630096.URPN.	USPAT	2003/10/13 17:26
11	65	4396936.URPN.	USPAT	2003/10/13 17:40
12	34	4630096.URPN.	USPAT	2003/10/13 17:38
13	15308	conduct\$4 adj substrate	USPAT	2003/10/13 17:40
14	241	(conduct\$4 adj substrate) and (anisotropical\$3 adj etch\$3)	USPAT; EPO; JPO; DERWENT; USOCR	2003/10/13 17:41
15	6	((conduct\$4 adj substrate) and (anisotropical\$3 adj etch\$3)) and posts	USPAT; EPO; JPO; DERWENT; USOCR	2003/10/13 17:58
16	9	("5501893" "5582701" "5591139" "5804084" "5824204" "5985119" "6013164" "6033544" "6096656").PN.	USPAT	2003/10/13 17:42
17	1	"20020034088"	USPAT; EPO; JPO; DERWENT; USOCR	2003/10/13 17:47
18	18	("5252294" "5501893" "5569355" "5585069" "5632876" "5660728" "5681484" "5729244" "5755408" "5783452" "5801442" "5858193" "5863708" "5871158" "5876582" "5876675" "5897097" "5909280").PN.	USPAT	2003/10/13 17:54
19	12	6096656.URPN.	USPAT	2003/10/13 17:57
20	0	174.250-268.ccls. and (anisotropical\$3 adj etch\$3)	USPAT; EPO; JPO; DERWENT; USOCR	2003/10/13 17:59

21	0	174.250-268.ccls. and (anisotropic)\$3 adj etch\$3)	USPAT; EPO; JPO; DERWENT; USOCR	2003/10/13 17:59
22	232	174/250-268.ccls. and posts	USPAT; EPO; JPO; DERWENT; USOCR	2003/10/13 17:59
23	137	(174/250-268.ccls. and posts) and etch\$4	USPAT; EPO; JPO; DERWENT; USOCR	2003/10/13 18:00
24	94	((174/250-268.ccls. and posts) and etch\$4) and substrate	USPAT; EPO; JPO; DERWENT; USOCR	2003/10/13 18:00
25	69	((174/250-268.ccls. and posts) and etch\$4) and substrate) and pads	USPAT; EPO; JPO; DERWENT; USOCR	2003/10/13 18:00